IS61C64AH



8K x 8 HIGH-SPEED CMOS STATIC RAM

FEATURES

- · High-speed access time: 15, 20, 25 ns
- Automatic power-down when chip is deselected
- CMOS low power operation
 - 450 mW (typical) operating
 - $-250 \,\mu\text{W}$ (typical) standby
- · TTL compatible interface levels
- Single 5V power supply
- Fully static operation: no clock or refresh required
- Three state outputs
- Two Chip Enables (CE1 and CE2) for simple memory expansion

DESCRIPTION

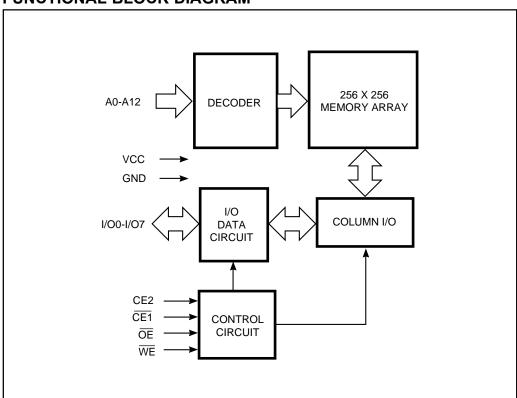
The ICSI IS61C64AH is a very high-speed, low power, 8192-word by 8-bit static RAM. It is fabricated using ICSI's high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields access times as fast as 15 ns with low power consumption.

When $\overline{\text{CE1}}$ is HIGH or CE2 is LOW (deselected), the device assumes a standby mode at which the power dissipation can be reduced down to 250 μ W (typical) with CMOS input levels.

Easy memory expansion is provided by using two Chip Enable inputs, $\overline{\text{CE1}}$ and CE2. The active LOW Write Enable ($\overline{\text{WE}}$) controls both writing and reading of the memory.

The IS61C64AH is packaged in the JEDEC standard 28-pin, 300mil SOJ and 330mil SOP.

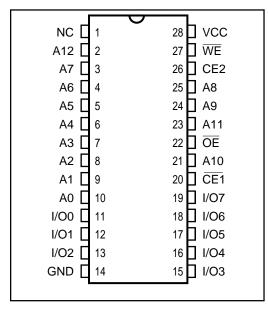
FUNCTIONAL BLOCK DIAGRAM



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PIN CONFIGURATION 28-Pin SOJ and SOP



PIN DESCRIPTIONS

A0-A12	Address Inputs
CE1	Chip Enable 1 Input
CE2	Chip Enable 2 Input
ŌĒ	Output Enable Input
WE	Write Enable Input
1/00-1/07	Input/Output
Vcc	Power
GND	Ground

TRUTH TABLE

Mode	WE	CE1	CE2	ŌĒ	I/O Operation	Vcc Current
Not Selected	Х	Н	Х	Х	High-Z	ISB1, ISB2
(Power-down)	Χ	X	L	X	High-Z	ISB1, ISB2
Output Disabled	Н	L	Н	Н	High-Z	Icc
Read	Н	L	Н	L	D оит	Icc
Write	L	L	Н	Х	DIN	Icc

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Parameter	Value	Unit
VTERM	Terminal Voltage with Respect to GND	-0.5 to +7.0	V
TBIAS	Temperature Under Bias	-55 to +125	°C
Тѕтс	Storage Temperature	-65 to +150	°C
Рт	Power Dissipation	1.0	W
Іоит	DC Output Current (LOW)	20	mA

Notes:

 Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

OPERATING RANGE

Range	Ambient Temperature	Vcc
Commercial	0°C to +70°C	5V ± 10%
Industrial ⁽¹⁾	–40°C to +85°C	5V ± 10%

Notes

1. Industrial supplement specification available upon request.



DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
Vон	Output HIGH Voltage	Vcc = Min., Iон = -4.0 mA	2.4	_	V
VoL	Output LOW Voltage	Vcc = Min., IoL = 8.0 mA	_	0.4	V
VIH	Input HIGH Voltage		2.2	Vcc + 0.5	V
VIL	Input LOW Voltage(1)		-0.5	0.8	V
lu	Input Leakage	GND ≤ VIN ≤ Vcc	-2	2	μΑ
ILO	Output Leakage	GND ≤ Vo∪т ≤ Vcc, Outputs Disabled	-2	2	μΑ

Note:

POWER SUPPLY CHARACTERISTICS⁽¹⁾ (Over Operating Range)

Symbol	Parameter	Test Conditions	-	5 ns Max.		ns Max.	-25 Min.	ns Max.	Unit	
Icc	Vcc Dynamic Operating Supply Current	Vcc = Max., lout = 0 mA, f = fmax	-	135	_	120	-	110	mA	
ISB1	TTL Standby Current (TTL Inputs)	$\begin{aligned} &\text{Vcc} = \text{Max.}, \\ &\text{ViN} = \text{ViH or ViL} \\ &\overline{\text{CE1}} \geq \text{ViH or} \\ &\text{CE2} \geq \text{ViL}, \text{f} = 0 \end{aligned}$	_	20	_	20	_	20	mA	
ISB2	CMOS Standby Current (CMOS Inputs)	$\label{eq:vcc} \begin{split} & \frac{\text{Vcc} = \text{Max.},}{\text{CE1}} \geq \text{Vcc} - 0.2\text{V},\\ & \text{CE2} \leq 0.2\text{V},\\ & \text{Vin} \geq \text{Vcc} - 0.2\text{V}, \text{ or }\\ & \text{Vin} \leq 0.2\text{V}, f = 0 \end{split}$	_	6	-	6	_	6	mA	

Note:

CAPACITANCE(1,2)

Symbol	Parameter	Conditions	Max.	Unit
Cin	Input Capacitance	Vin = 0V	5	pF
Соит	Output Capacitance	Vout = 0V	7	pF

Notes:

- 1. Tested initially and after any design or process changes that may affect these parameters.
- 2. Test conditions: $T_A = 25^{\circ}C$, f = 1 MHz, $V_{CC} = 5.0V$.

^{1.} $V_{IL} = -3.0V$ for pulse width less than 10 ns.

^{1.} At f = fmax, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.



READ CYCLE SWITCHING CHARACTERISTICS⁽¹⁾ (Over Operating Range)

			ns	-20		-25 n		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
trc	Read Cycle Time	15	_	20	_	25	_	ns
taa	Address Access Time	_	15	_	20	_	25	ns
t oha	Output Hold Time	3	_	3	_	3	_	ns
t _{ACE1}	CE1 Access Time	_	15	_	20	_	25	ns
t _{ACE2}	CE2 Access Time	_	15	_	20	_	25	ns
tDOE	OE Access Time	_	7	_	7	-	9	ns
tLZOE ⁽²⁾	OE to Low-Z Output	0	_	0	_	0	_	ns
thzoe(2)	OE to High-Z Output	_	6	_	7	_	9	ns
tLZCE1(2)	CE1 to Low-Z Output	3	_	3	_	3	_	ns
tLZCE2(2)	CE2 to Low-Z Output	3	_	3	_	3	_	ns
thzce(2)	CE1 or CE2 to High-Z Output	_	8	_	10	_	12	ns
t PU ⁽³⁾	CE1 or CE2 to Power-Up	0	_	0	_	0	_	ns
t PD ⁽³⁾	CE1 or CE2 to Power-Down	_	15	-	20	-	20	ns

Notes:

- 1. Test conditions assume signal transition times of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1.
- 2. Tested with the load in Figure 2. Transition is measured ±500 mV from steady-state voltage. Not 100% tested.
- 3. Not 100% tested.

AC TEST CONDITIONS

Parameter	Unit
Input Pulse Level	0V to 3.0V
Input Rise and Fall Times	3 ns
Input and Output Timing and Reference Level	1.5V
Output Load	See Figures 1 and 2

AC TEST LOADS

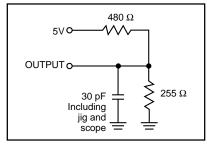


Figure 1.

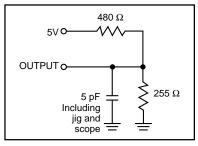
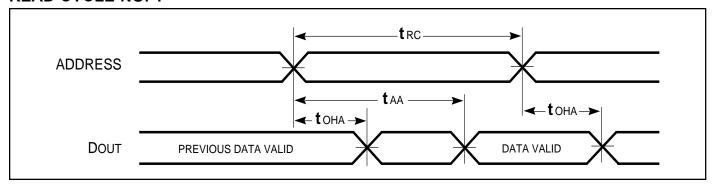


Figure 2.

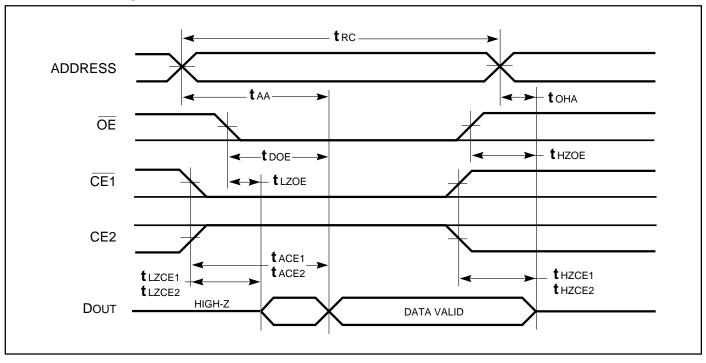


AC WAVEFORMS

READ CYCLE NO. 1^(1,2)



READ CYCLE NO. 2^(1,3)



Notes Notes

- 1. WE is HIGH for a Read Cycle.
- 2. The device is continuously selected. \overline{OE} , $\overline{CE1}$ = V_{IL}, CE2 = V_{IH}.
- 3. Address is valid prior to or coincident with $\overline{\text{CE1}}$ LOW and CE2 HIGH transitions.



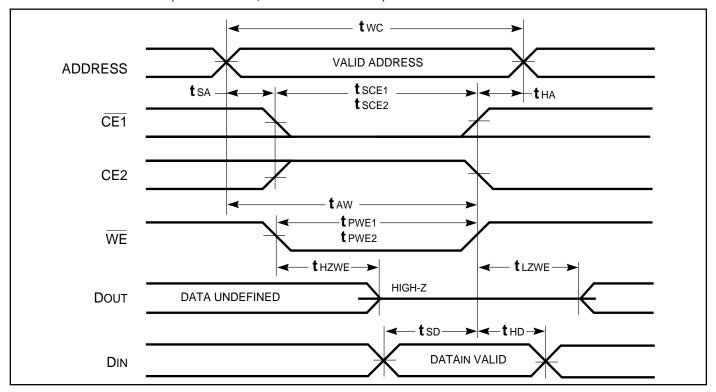
WRITE CYCLE SWITCHING CHARACTERISTICS(1,3) (Over Operating Range)

	-12	ns ns	-15	ns	-2	.0 ns	-25	ns	
Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Unit
Write Cycle Time	12	_	15	_	20	_	25	_	ns
CE1 to Write End	10	_	12	-	17	_	22	-	ns
CE2 to Write End	10	_	12	_	17	_	22	_	ns
Address Setup Time to Write End	10	_	12	_	15	_	20	_	ns
Address Hold from Write End	0	_	0	-	0	_	0	-	ns
Address Setup Time	0	_	0	-	0	_	0	-	ns
WE Pulse Width	8	_	10	_	12	_	15	_	ns
Data Setup to Write End	8	_	9	-	10	_	12	_	ns
Data Hold from Write End	0	_	0	_	0	_	0	_	ns
WE LOW to High-Z Output	_	6	-	8	_	10	_	12	ns
WE HIGH to Low-Z Output	0	_	0	-	0	_	0	_	ns
	Write Cycle Time CE1 to Write End CE2 to Write End Address Setup Time to Write End Address Hold from Write End Address Setup Time WE Pulse Width Data Setup to Write End Data Hold from Write End WE LOW to High-Z Output	Parameter Min. Write Cycle Time 12 CE1 to Write End 10 CE2 to Write End 10 Address Setup Time to Write End 10 Address Hold from Write End 0 Address Setup Time 0 WE Pulse Width 8 Data Setup to Write End 8 Data Hold from Write End 0 WE LOW to High-Z Output —	Write Cycle Time 12 — CE1 to Write End 10 — CE2 to Write End 10 — Address Setup Time to Write End 10 — Address Hold from Write End 0 — Address Setup Time 0 — WE Pulse Width 8 — Data Setup to Write End 8 — Data Hold from Write End 0 — WE LOW to High-Z Output — 6	Parameter Min. Max. Min. Write Cycle Time 12 — 15 ŒE1 to Write End 10 — 12 CE2 to Write End 10 — 12 Address Setup Time to Write End 10 — 12 Address Hold from Write End 0 — 0 Address Setup Time 0 — 0 WE Pulse Width 8 — 10 Data Setup to Write End 8 — 9 Data Hold from Write End 0 — 0 WE LOW to High-Z Output — 6 —	Parameter Min. Max. Min. Max. Write Cycle Time 12 — 15 — CE1 to Write End 10 — 12 — CE2 to Write End 10 — 12 — Address Setup Time to Write End 0 — 0 — Address Hold from Write End 0 — 0 — Address Setup Time 0 — 0 — WE Pulse Width 8 — 10 — Data Setup to Write End 8 — 9 — Data Hold from Write End 0 — 0 — WE LOW to High-Z Output — 6 — 8	Parameter Min. Max. Min. Max. Min. Write Cycle Time 12 — 15 — 20 ŒE1 to Write End 10 — 12 — 17 CE2 to Write End 10 — 12 — 17 Address Setup Time to Write End 0 — 0 — 0 Address Hold from Write End 0 — 0 — 0 Address Setup Time 0 — 0 — 0 WE Pulse Width 8 — 10 — 12 Data Setup to Write End 8 — 9 — 10 Data Hold from Write End 0 — 0 — 0 WE LOW to High-Z Output — 6 — 8 —	Parameter Min. Max. Min. Max. Min. Max. Write Cycle Time 12 — 15 — 20 — CE1 to Write End 10 — 12 — 17 — CE2 to Write End 10 — 12 — 17 — Address Setup Time to Write End 0 — 0 — 0 — Address Hold from Write End 0 — 0 — 0 — Address Setup Time 0 — 0 — 0 — WE Pulse Width 8 — 10 — 12 — Data Setup to Write End 8 — 9 — 10 — Data Hold from Write End 0 — 0 — 0 — WE LOW to High-Z Output — 6 — 8 — 10	Parameter Min. Max. Min. Max. Min. Max. Min. Max. Min. Max. Min. Max. Min. Min.	Parameter Min. Max. Min. Max. Min. Max. Min. Max. Write Cycle Time 12 — 15 — 20 — 25 — ŒE1 to Write End 10 — 12 — 17 — 22 — CE2 to Write End 10 — 12 — 17 — 22 — Address Setup Time to Write End 0 — 0 — 0 — 0 — Address Setup Time 0 — 0 — 0 — 0 — Address Setup Time 0 — 0 — 0 — 0 — WE Pulse Width 8 — 10 — 12 — 15 — Data Setup to Write End 0 — 0 — 0 — 0 — Data Hold from Write End 0 — 0 — 0 </td

Notes:

- 1. Test conditions assume signal transition times of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1.
- 2. Tested with the load in Figure 2. Transition is measured ±500 mV from steady-state voltage. Not 100% tested.
- 3. The internal write time is defined by the overlap of CE1 LOW, CE2 HIGH and WE LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write.

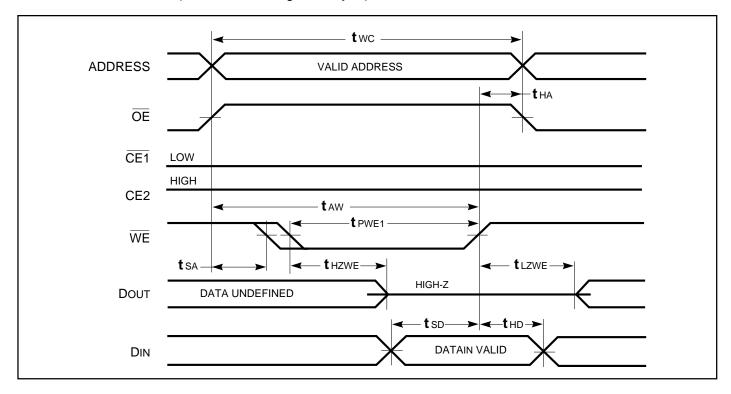
AC WAVEFORMS
WRITE CYCLE NO. 1 (CE Controlled, OE is HIGH or LOW) (1)



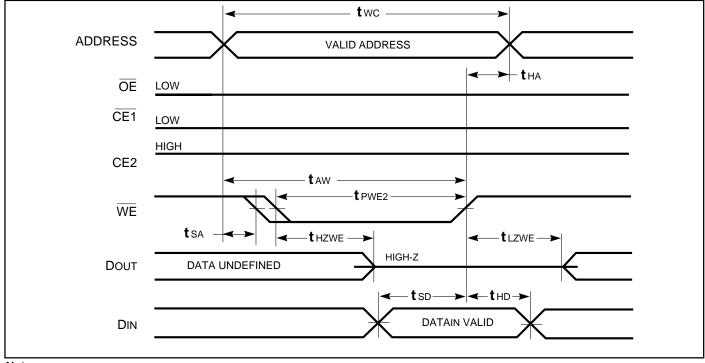


AC WAVEFORMS

WRITE CYCLE NO. 2 (OE is HIGH During Write Cycle) (1,2)



WRITE CYCLE NO. 3 (OE is LOW During Write Cycle) (1)



Notes:

- 1. The internal write time is defined by the overlap of $\overline{\text{CE1}}$ LOW, CE2 HIGH and $\overline{\text{WE}}$ LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write.
- 2. I/O will assume the High-Z state if $\overline{OE} = V_{IH}$.



ORDERING INFORMATION

Commercial Range: 0°C to +70°C

Speed (ns)	Order Part No.	Package
15	IS61C64AH-15J IS61C64AH-15U	300mil SOJ 330mil SOP
20	IS61C64AH-20J IS61C64AH-20U	300mil SOJ 330mil SOP
25	IS61C64AH-25J IS61C64AH-25U	300mil SOJ 330mil SOP



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